



Smart Systems (SmaSys2022)

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Deadline for manuscript
submissions:

closed (31 May 2023)

Message from the Guest Editors

Dear Colleagues,

We are planning to publish a Special Issue on "Smart Systems 2022" related to the International Conference of Smart Systems Engineering (SmaSys2022, http://zyyu.sakura.ne.jp/smasys.yz.yamagata-u.ac.jp/2022_1/) held on 6–7 October 2022, in Yamagata, Japan. The Special Issue "Smart Systems 2022" provides opportunities for collaboration across a wide range of fields and technologies related to emerging smart systems. Smart systems concern broad scientific and engineering fields. They include organic materials, organic electronics, organic devices, biomaterials, biomedical and biosystem engineering, electrical engineering and informatics, mechanical systems engineering, smart flexible structures and systems, green materials and their processing, tourism engineering with agriculture and foods, and new engineering education.

All participants of SmaSys2022 and their colleagues, especially their students, are encouraged to submit their works to this Special Issue.





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Message from the Editor-in-Chief

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